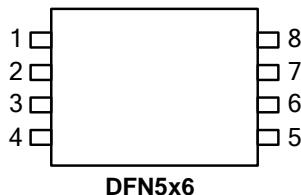


N-Channel Power MOSFET

General Description		Product Summary	
● Very low on-resistance $R_{DS(ON)}$		V_{DS}	60V
● Low Gate Charge		I_D	75A
● Excellent Gate Charge x $R_{DS(ON)}$ Product		$R_{DS(ON)}$ (at $V_{GS}=10V$)	< 8.5mΩ(Max)
		$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	< 12 mΩ(Max)
Applications		100% DVDS Tested	
● High Frequency Switching and Synchronous Rectification		100% UIS Tested	
		100% Rg Tested	



Part Number	Package Type	Form	Marking
SL75N06Q	DFN5x6	Tape & Reel	SL75N06Q

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current <small>$T_C = 100^\circ C$ ^B</small>	I_D	75	A
		47	
Pulsed Drain Current ^A	I_{DM}	280	A
Avalanche Current ^A	I_{AS}	40	A
Single Pulse Avalanche Energy <small>$L = 0.3mH$ ^A</small>	E_{AS}	80	mJ
Power Dissipation ^C	P_D	41	W
		2.5	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Maximum	Units
Maximum Junction-to-Case	R_{eJC}	62	°C/W
Maximum Junction-to-Ambient	R_{eJA}	1.4	

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =10mA	60	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =20A	-	7.1	8.5	mΩ
		V _{GS} =4.5V, I _D =20A	-	9.5	12	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.2	-	2.4	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =20A	-	30	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =20V, V _{GS} =0V	-	-	1	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Q _g	Total Gate Charge	I _D =20A	-	57	-	nC
Q _{gs}	Gate-Source Charge	V _{DS} =15V	-	8	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =4.5V	-	14	-	nC
t _{d(on)}	Turn-on Delay Time	V _{DS} =15V	-	16	-	ns
t _r	Rise Time	I _D =1A	-	41	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3Ω	-	56	-	ns
t _f	Fall Time	V _{GS} =10V	-	16	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	3307	-	pF
C _{oss}	Output Capacitance	V _{DS} =15V	-	201	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	105	-	pF
R _g	Gate Resistance	f=1.0MHz	-	1.2	-	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ²	I _S =20A, V _{GS} =0V	-	-	1.2	V
t _{rr}	Reverse Recovery Time	I _S =20A, V _{GS} =0V,	-	22	-	ns
Q _{rr}	Reverse Recovery Charge	dl/dt=100A/μs	-	30	-	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=50V,V_{GS}=10V,L=0.1mH,I_{AS}=40A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

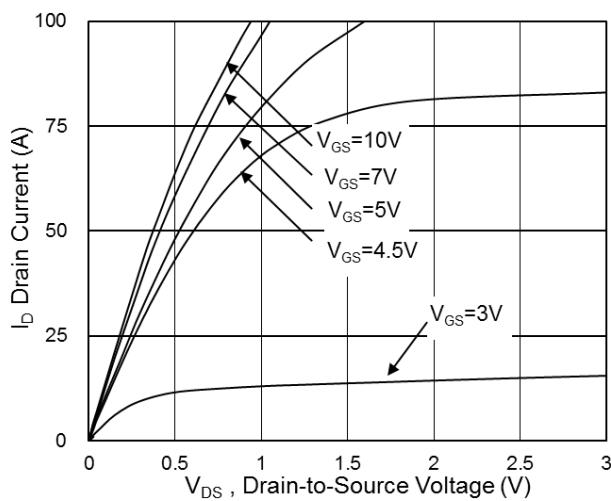


Fig.1 Typical Output Characteristics

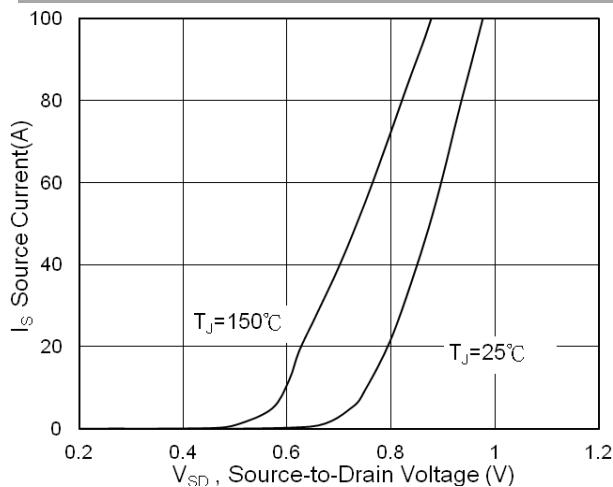


Fig.3 Forward Characteristics of Reverse

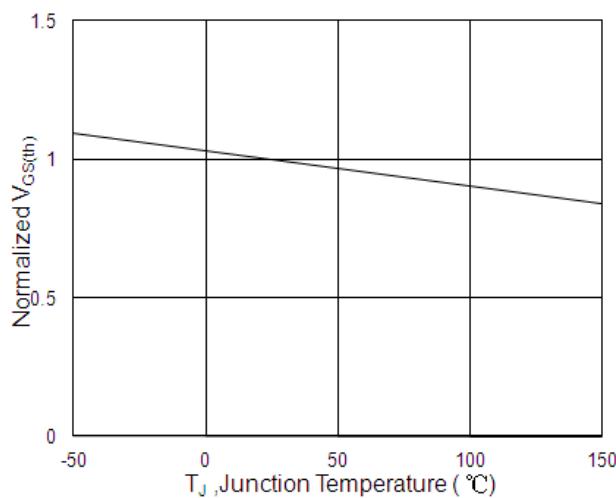


Fig.5 Normalized $V_{GS(th)}$ vs T_J

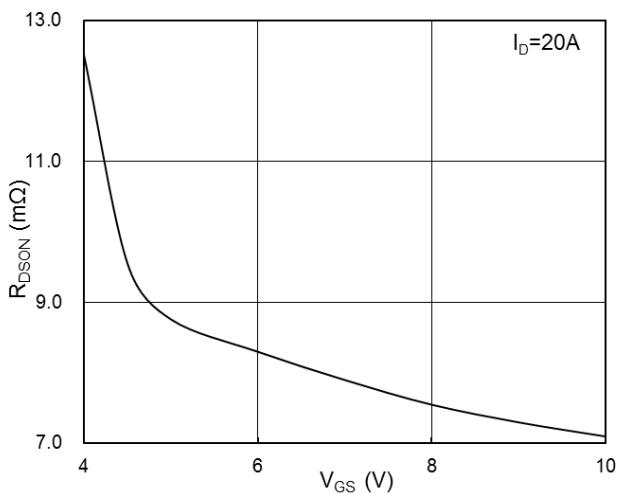


Fig.2 On-Resistance vs Gate-Source Voltage

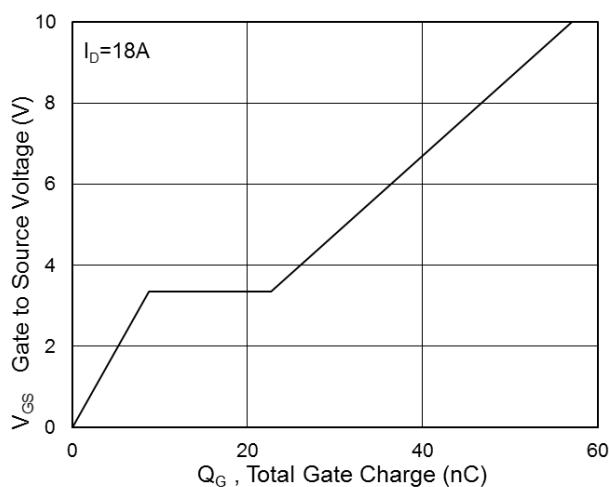


Fig.4 Gate-Charge Characteristics

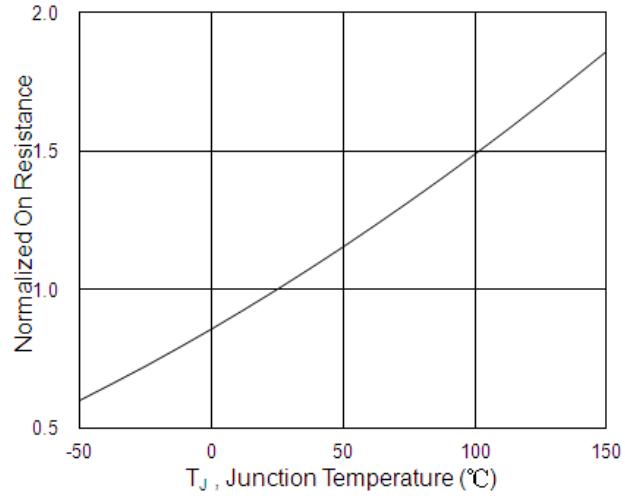


Fig.6 Normalized $R_{DS(on)}$ vs T_J

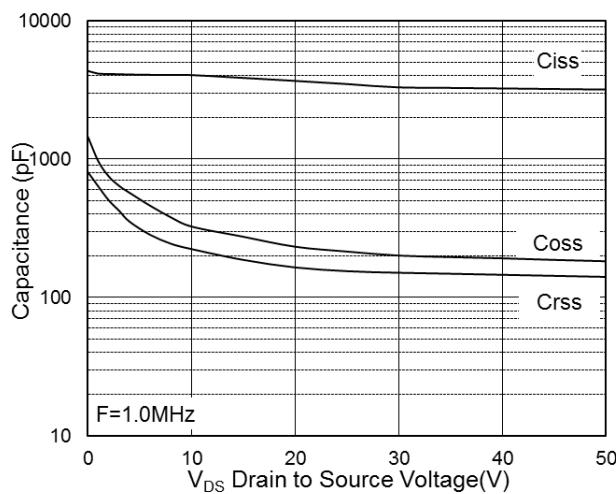


Fig.7 Capacitance

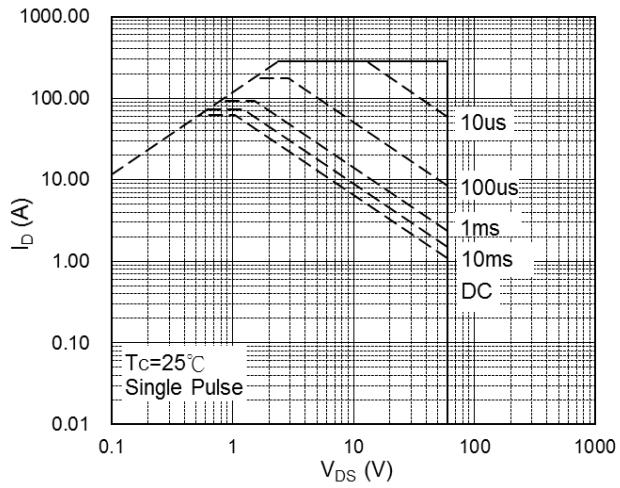


Fig.8 Safe Operating Area

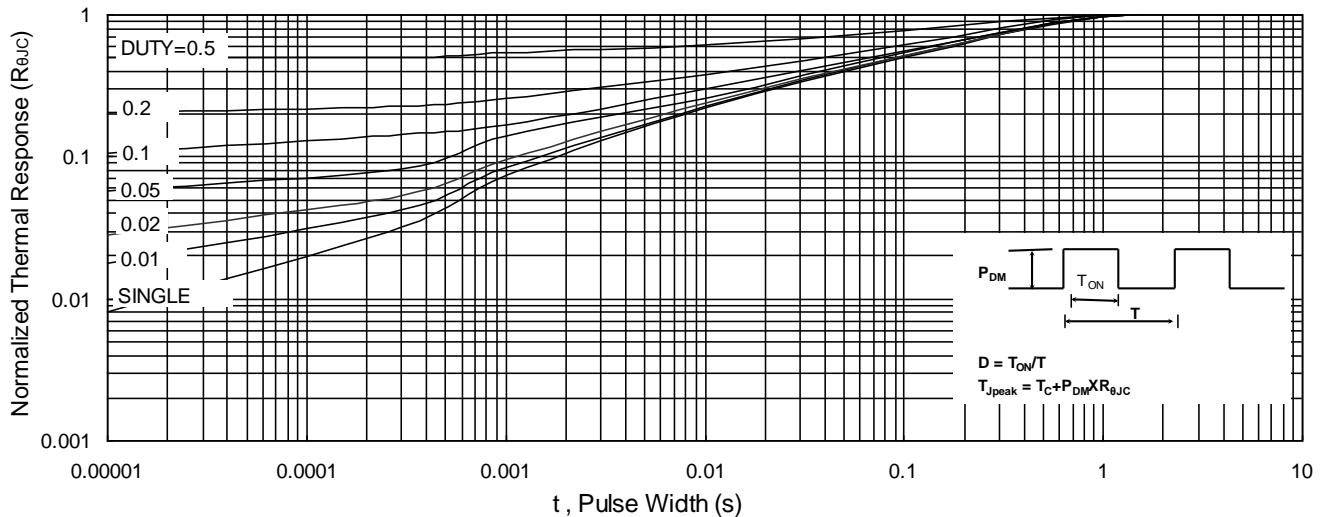


Fig.9 Normalized Maximum Transient Thermal Impedance

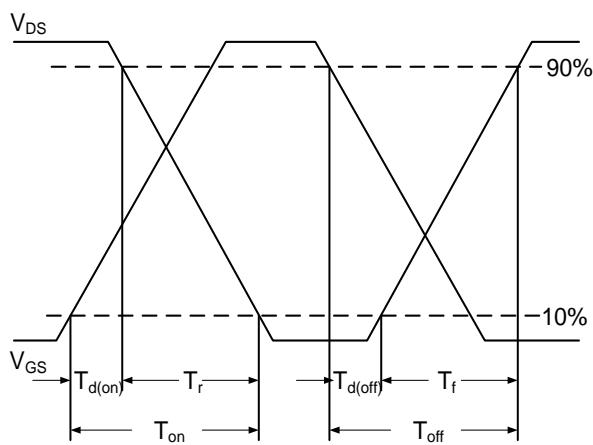


Fig.10 Switching Time Waveform

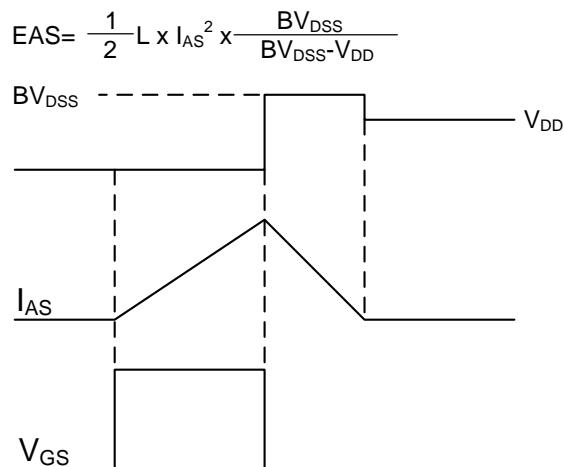
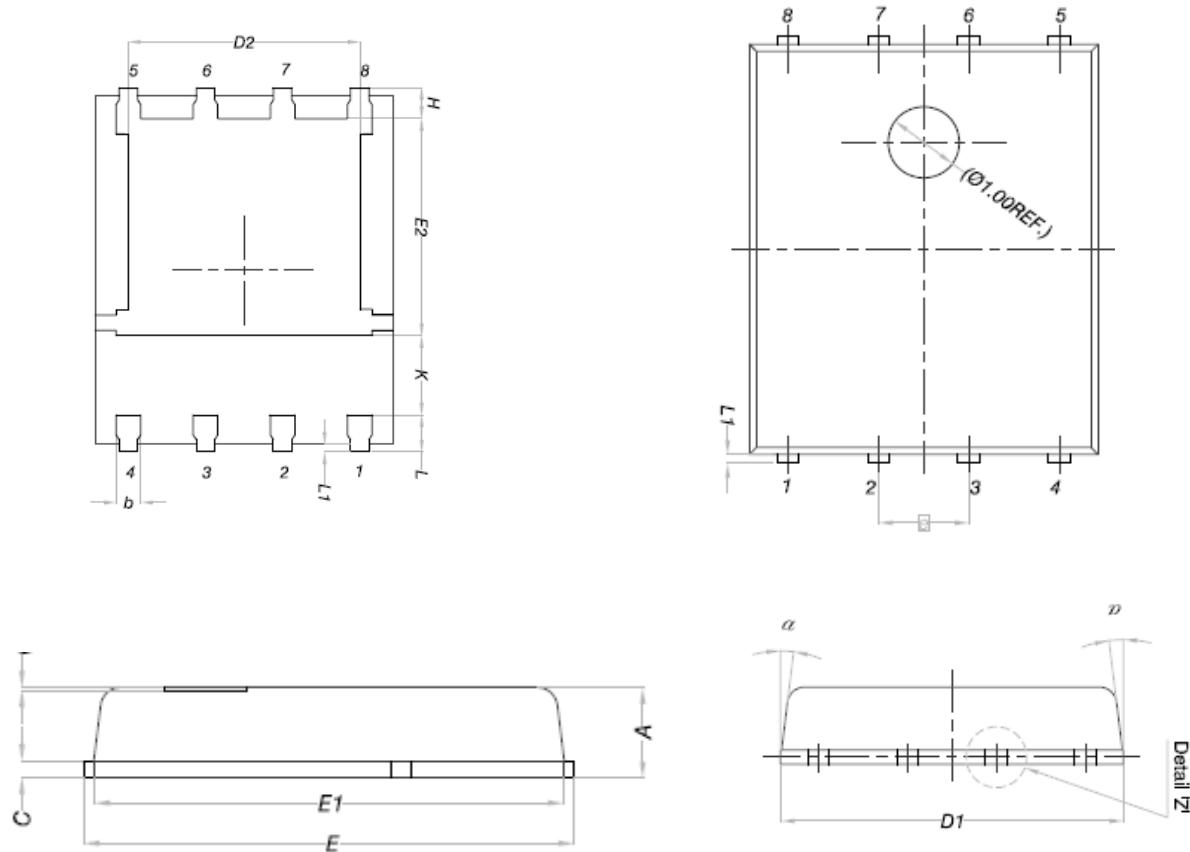


Fig.11 Unclamped Inductive Switching Waveform

DFN5x6



DIM.	MILLIMETERS			DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.
A	0.90	1.00	1.10	E	5.90	6.00	6.10
A1	0	-	0.05	E1	5.70	5.75	5.80
b	0.33	0.41	0.51	E2	3.38	3.58	3.78
C	0.20	0.25	0.30	e	1.27 BSC		
D1	4.80	4.90	5.00	H	0.41	0.51	0.61
D2	3.61	3.81	3.96	K	1.10	-	-
				L	0.51	0.61	0.71
				L1	0.06	0.13	0.20
				α	0°	-	12°